

DM74ALS00A Quad 2-Input NAND Gate

General Description

This device contains four independent gates, each of which performs the logic NAND function.

Features

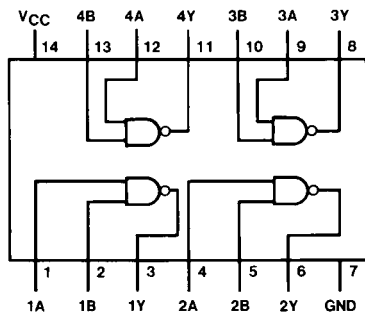
- Switching specifications at 50 pF
- Switching specifications guaranteed over full temperature and V_{CC} range
- Advanced oxide-isolated, ion-implanted Schottky TTL process
- Functionally and pin for pin compatible with Schottky and low power Schottky TTL counterpart
- Improved AC performance over Schottky and low power Schottky counterparts

Ordering Code:

Order Number	Package Number	Package Description
DM74ALS00AM	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
DM74ALS00ASJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
DM74ALS00AN	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Function Table

$$Y = \overline{AB}$$

Inputs		Output
A	B	Y
L	L	H
L	H	H
H	L	H
H	H	L

H = HIGH Logic Level
L = LOW Logic Level

Absolute Maximum Ratings(Note 1)

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	0°C to +70°C
Storage Temperature Range	-65°C to +150°C
Typical θ_{JA}	
N Package	86.5°C/W
M Package	116.0°C/W

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Recommended Operating Conditions

Symbol	Parameter	Min	Nom	Max	Units
V_{CC}	Supply Voltage	4.5	5	5.5	V
V_{IH}	HIGH Level Input Voltage	2			V
V_{IL}	LOW Level Input Voltage			0.8	V
I_{OH}	HIGH Level Output Current			-0.4	mA
I_{OL}	LOW Level Output Current			8	mA
T_A	Free Air Operating Temperature	0		70	°C

Electrical Characteristics

over recommended operating free air temperature range. All typical values are measured at $V_{CC} = 5V$, $T_A = 25^\circ C$.

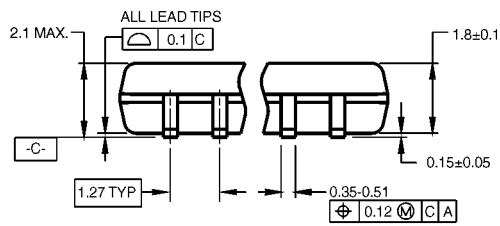
Symbol	Parameter	Conditions		Min	Typ	Max	Units
V_{IK}	Input Clamp Voltage	$V_{CC} = 4.5V$, $I_I = -18\text{ mA}$				-1.5	V
V_{OH}	HIGH Level Output Voltage	$I_{OH} = -0.4\text{ mA}$		$V_{CC} - 2$			V
V_{OL}	LOW Level Output Voltage	$V_{CC} = 4.5V$	$I_{OL} = 8\text{ mA}$		0.35	0.5	V
I_I	Input Current at Maximum Input Voltage	$V_{CC} = 5.5V$, $V_{IH} = 7V$				0.1	mA
I_{IH}	HIGH Level Input Current	$V_{CC} = 5.5V$, $V_{IH} = 2.7V$				20	μA
I_{IL}	LOW Level Input Current	$V_{CC} = 5.5V$, $V_{IL} = 0.4V$				-0.1	mA
I_O	Output Drive Current	$V_{CC} = 5.5V$	$V_O = 2.25V$	-30		-112	mA
I_{CC}	Supply Current	$V_{CC} = 5.5V$	Outputs HIGH		0.43	0.85	mA
			Outputs LOW		1.62	3	mA

Switching Characteristics

over recommended operating free air temperature range

Symbol	Parameter	Conditions	Min	Max	Units
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	$V_{CC} = 4.5V$ to $5.5V$ $R_L = 500\Omega$	3	11	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output	$C_L = 50\text{ pF}$	2	8	ns

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

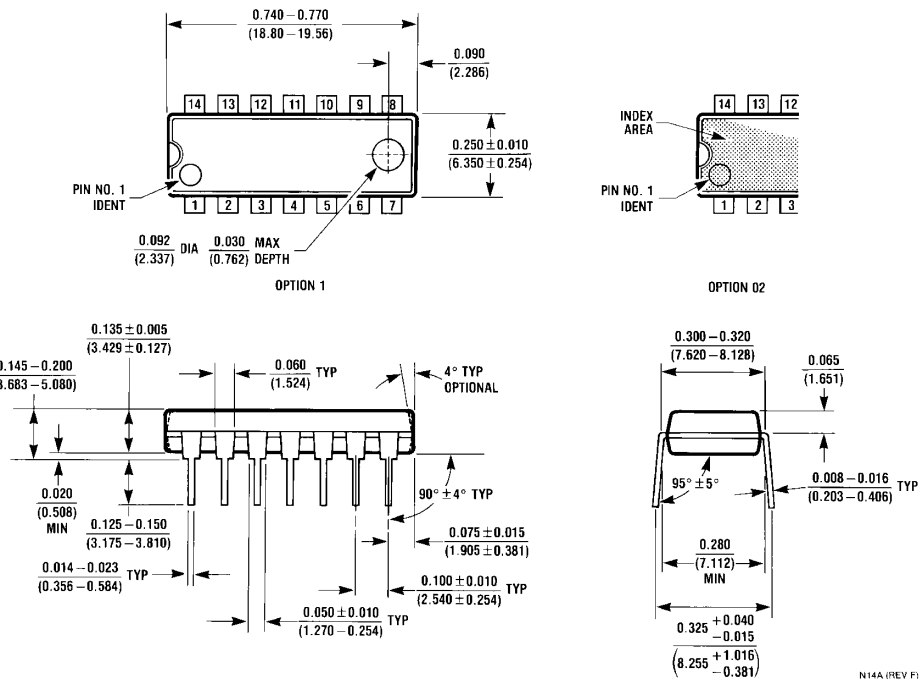
- NOTES:
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1



**14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
 Package Number M14D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N14A

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